



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
	TID #: .TID		
PLOT NAME = Top Assembly Drawing	GENERATED : 8/21/2017 14:01:20	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30296	REV: A	SUN REV: Not In VersionControl
	TID #: .TID		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/21/2017 14:01:22	TEXAS INSTRUMENTS	

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